



FEATURES

- Mixer/Oscillator for TV Tuner
- Three-Band Local Oscillator and Mixer
- Local Oscillator Output
- 5-V Power Supply
- 24-Pin TSSOP Package

APPLICATIONS

- TV
- VCR

DESCRIPTION

The SN761685 is a monolithic IC designed for TV tuning systems. The circuit consists of a three-band local oscillator and mixer, and is available in a small outline package.

PW PACKAGE (TOP VIEW)

UHF OSC1 □□□	10	24	MIXOUT1
	'		INIIXOOTT
VLO OSC1 □□□	2	23	MIXOUT2
UHF OSC2 🖂	3	22	□□ GND
VLO OSC2	4	21	UHF IN1
UHF OSC3 □□□	5	20	UHF IN2
VHI OSC1 □□□	6	19	ULO IN
UHF OSC4 \Box	7	18	□□□ VHI IN1
VHI OSC2 🖂	8	17	□□□ VHI IN2
VHI OSC3 🞞	9	16	
GND □□	10	15	OSCOUT1
IFOUT1 🗀	11	14	OSCOUT2
IFOUT2 🗀	12	13	BAND SEL



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

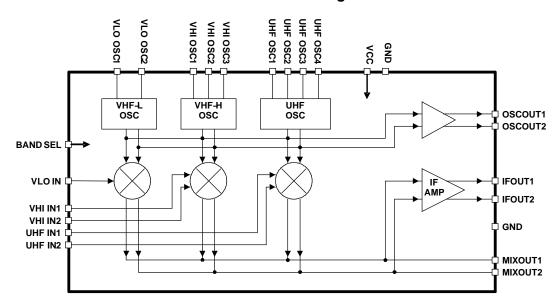




This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

UHF IN1 and UHF IN2 (pins 20 and 21) withstand 1 kV, and all other pins withstand 2 kV, according to the human body model (1.5 k Ω , 100 pF).

Functional Block Diagram



Pin Assignments

Pin Description

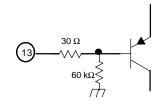
TERMIN	IAL	DESCRIPTION	SCHEMATIC		
NAME NO.		DESCRIPTION	ЗСПЕМАПС		
BAND SEL	13	Band selection input	Figure 1		
GND	10, 22	Ground			
IF OUT1	11	IF amplifier output 1	Figure 2		
IF OUT2	12	IF amplifier output 2	Figure 2		
MIXOUT1	24	Mixer output 1	Figure 3		
MIXOUT2	23	Mixer output 2	Figure 3		
OSCOUT1	15	Local oscillator output 1	Figure 4		
OSCOUT2	14	Local oscillator output 2	Figure 4		
UHF IN1	21	UHF mixer input 1	Figure 5		
UHF IN2	20	UHF mixer input 2	Figure 5		
UHF OSC 1	1	UHF oscillator 1	Figure 6		
UHF OSC 2	3	UHF oscillator 2	Figure 6		
UHF OSC 3	5	UHF oscillator 3	Figure 6		
UHF OSC 4	7	UHF oscillator 4	Figure 6		
VCC	16	VCC 5 V			
VHI IN1	18	VHF HIGH mixer input 1	Figure 7		
VHI IN2	17	VHF HIGH mixer input 2	Figure 7		
VHI OSC 1	6	VHF HIGH oscillator 1	Figure 8		
VHI OSC 2	8	VHF HIGH oscillator 2	Figure 8		
VHI OSC 3	9	VHF HIGH oscillator 3	Figure 8		
VLO IN	19	VHF LOW mixer input	Figure 9		



Pin Assignments (continued)

Pin Description (continued)

TERMINA	۱L	DESCRIPTION	SCHEMATIC
NAME	NO.	DESCRIPTION	SCHEWATIC
VLO OSC 1	2	VHF LOW oscillator 1	Figure 10
VLO OSC 2	4	VHF LOW oscillator 2	Figure 10



10 Ω 10 Ω 10 Ω 10 Ω

Figure 1.

23

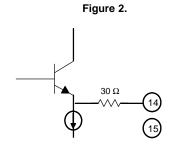


Figure 3.

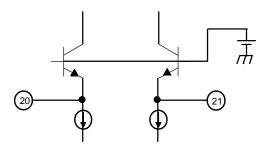


Figure 4.

3k

3k

777

Figure 5.

Figure 6.

3 kΩ ≤

(19)



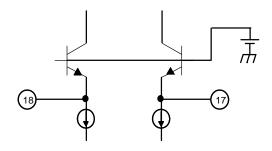


Figure 7. $\leq 3 \text{ k}\Omega$

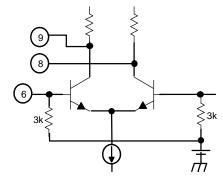


Figure 8.

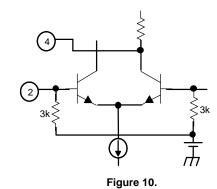


Figure 9.



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) (1)

Supply voltage, V _{CC} ⁽²⁾	VCC (Pin 16)	–0.4 V to 6.5 V
Input voltage (2)	V _{IN} (Pins 1–9, 11–15, 17–21, 23, 24)	-0.4 V to 6.5 V
Continuous total dissipation, P _D ⁽³⁾	T _A ≤ 25°C	1092 mW
Storage temperature range, T _{stg}		−65°C to 150°C
Maximum junction temperature, T _J		150°C
Maximum short-circuit time, t _{SC(max)}	Each pin to V _{CC} or to GND	10 s

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	٧
Operating free-air temperature, T _A	-20		85	°C

ELECTRICAL CHARACTERISTICS, DC Parameters

 V_{CC} = 5 V, T_A = 25°C, unless otherwise noted

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{CC}	Supply current	VHF-LOW band, no signal		43		mA
V _{SEL1}		VHF-LOW band	0	0.18	V_{CC}	
V_{SEL2}		VHF-HIGH band	0.26 V _{CC}	0.47	V_{CC}	V
V _{SEL3}	322)	UHF band	0.55 V _{CC}		V_{CC}	
I _{SEL}	Input current (BAND SEL)	V _{SEL} = 5 V			130	μΑ

⁽²⁾ Voltage values are with respect to the IF GND of the circuit.

⁽³⁾ Derating factor is 8.73 mW/°C for $T_A \ge 25$ °C.



ELECTRICAL CHARACTERISTICS, AC Parameters

 V_{CC} = 5 V, T_A = 25°C, measured in reference measurement circuit of 50- Ω system, IF filter characteristics: f_{PEAK} = 36 MHz, unless otherwise noted

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
G _{c1}	0	f _{IN} = 50 MHz	22	25	28	-ID	
G _{c3}	Conversion gain, VHF-LOW (1)	f _{IN} = 170 MHz	22	25	28	dB	
G _{c4}	Conversion asia VIII IIICII (2)	f _{IN} = 170 MHz	21	24	27	dB	
G _{c6}	Conversion gain, VHF-HIGH (2)	f _{IN} = 450 MHz	21	24	27		
G _{c7}	Commission and MIS III (2)	f _{IN} = 450 MHz	21	24	27	dB	
G _{c9}	Conversion gain, VHF-UHF (2)	f _{IN} = 860 MHz	21	21 24 27			
NF ₁	Noise figure, VHF-LOW (see	f _{IN} = 50 MHz		9.5		٩D	
NF ₃	Figure 14)	f _{IN} = 170 MHz		9.5		dB	
NF ₄	Noise figure, VHF-HIGH (see	f _{IN} = 170 MHz		12		٩D	
NF ₆	Figure 15)	f _{IN} = 450 MHz		12		dB	
NF ₇	Naisa figura IIII (and Figura 45)	f _{IN} = 450 MHz		11		4D	
NF ₉	Noise figure, UHF (see Figure 15)	f _{IN} = 860 MHz		11		dB	
CM ₁	10/ cross modulation \/ LE LOW (3)	f _{IN} = 50 MHz		88		4D\/	
CM ₃	1% cross-modulation, VHF-LOW (3)	f _{IN} = 170 MHz		90	dΒμV		
CM ₄	40/ 27222 7224/10127 //15 11/01/(4)	f _{IN} = 170 MHz		84		dBμV	
CM ₆	1% cross-modulation, VHF-HIGH (4)	f _{IN} = 450 MHz		84			
CM ₇	40/ 2022 2024 delation LUIF (/)	f _{IN} = 450 MHz		85		-IDV	
CM ₉	1% cross-modulation, UHF (4)	f _{IN} = 860 MHz		85		dΒμV	
V _{IFO1}	IF output voltage VIIF LOW (5)	f _{IN} = 50 MHz		117		dΒμV	
V _{IFO3}	IF output voltage, VHF-LOW (5)	f _{IN} = 170 MHz		117			
V _{IFO4}	IF output voltage VIIF HIGH (6)	f _{IN} = 170 MHz		117		dPu\/	
V _{IFO6}	IF output voltage, VHF-HIGH (6)	f _{IN} = 450 MHz		117		dΒμV	
V _{IFO7}	IF output voltage, UHF (6)	f _{IN} = 450 MHz		117	117		
V _{IFO9}	ir output voltage, OHF (%)	f _{IN} = 860 MHz		117		dBμV	
Δf_{SWO1}	SW ON drift, VHF-LOW (7)	f _{OSC} = 86 MHz			±300	kHz	
Δf_{SWO3}	SW ON drift, VHF-LOW W	f _{OSC} = 206 MHz			±400	KΠZ	
Δf_{SWO4}	SW ON drift, VHF-HIGH (7)	f _{OSC} = 206 MHz			±300	kHz	
Δf_{SWO6}	SW ON drift, VIII-IIIGIT (7)	f _{OSC} = 486 MHz		±400			
Δf_{SWO7}	SW ON drift, UHF ⁽⁷⁾	f _{OSC} = 486 MHz			±400	ld la	
Δf_{SWO9}	SW ON drift, OHF W	f _{OSC} = 896 MHz		±500	kHz		
Δf_{VSO1}	Frequency sift on V _{CC} , VHF-LOW	f _{OSC} = 86 MHz			±150	kHz	
Δf_{VSO3}	(NOTE13)	f _{OSC} = 206 MHz			±250	Kr1Z	
Δf_{VSO4}	Frequency sift on V _{CC} , VHF-HIGH	f _{OSC} = 206 MHz			±150	kHz	
Δf_{VSO6}	(8)	f _{OSC} = 486 MHz			±250	Kr1Z	
Δf_{VSO7}	Fraguency sift on V LILLE(8)	f _{OSC} = 486 MHz			±150	ν⊔¬	
Δf_{VSO9}	Frequency sift on V _{CC} , UHF ⁽⁸⁾	f _{OSC} = 896 MHz			kHz		

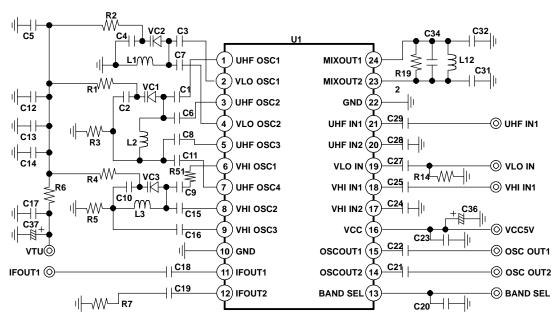
- (1) IF = 36 MHz, V_{IN} = 70 dB μ V (see Figure 12).
- IF = 36 MHz, V_{IN} = 70 dbμV (see Figure 12).
 IF = 36 MHz, V_{IN} = 70 dbμV (see Figure 13).
 DES: V_{IN} = 80 dBμV, UNDES: f_{des} ±6 MHz, AM 1 kHz, 30%, DES/CM = S/I = 46 dB (see Figure 16).
 DES: V_{IN} = 80 dBμV, UNDES: f_{des} ±6 MHz AM 1 kHz 30%, DES/CM = S/I = 46 dB (see Figure 17).
 IF = 36 MHz, V_{IN} = 107 dBμV (see Figure 18).
 IF = 36 MHz, V_{IN} = 107 dBμV, (see Figure 19).

- (7) Delta frequency from 3 s to 3 min after switch on
 (8) Delta frequency when V_{CC} = 5 V changes ±10%



APPLICATION INFORMATION

Reference Measurement Circuit



NOTE: This application information is advisory, and a performance check is required for actual application circuits. TI assumes no responsibility for the consequences of the use of this circuit, such as an infringement of intellectual property rights or other rights, including patents, of third parties.

Figure 11. Reference Measurement Circuit

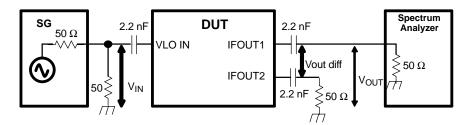


APPLICATION INFORMATION (continued) Component Values for Measurement Circuit

PART NAME	VALUE	PART NAME	VALUE
C1 (UHF OSC)	2 pF	C28 (UHF IN2)	2.2 nF
C2 (UHF OSC)	15 pF	C29 (UHF IN1)	2.2 nF
C3 (VLO OSC)	1.5 pF	C31 (MIXOUT)	Open
C4 (VLO OSC)	120 pF	C32 (MIXOUT)	Open
C5 (VTU)	Open	C34 (MIXOUT)	15 pF
C6 (UHF OSC)	1.5 pF	C36 (VCC)	47 μF
C7 (VLO OSC)	2 pF	C37 (VTU)	47 μF/50 V
C8 (UHF OSC)	1.5 pF	L1 (VHI OSC)	φ3 mm, 8T, wire 0,32 mm
C9 (VHI OSC)	3 pF	L2 (UHF OSC)	φ1.8 mm, 2T, wire 0,4 mm
C10 (VHI OSC)	91 pF	L3 (VHI OSC)	φ2 mm, 4T, wire 0,4 mm
C11 (UHF OSC)	2 pF	L12 (MIXOUT)	φ3 mm, 25T, wire 0,29 mm
C12 (VTU)	2.2 nF	R1(UHF OSC)	22 kΩ
C13 (VTU)	2.2 nF	R2 (VLO OSC)	33 kΩ
C14 (VTU)	2.2 nF	R3 (UHF OSC)	22 kΩ
C15 (VHI OSC)	3 pF	R4 (VHI OSC)	33 kΩ
C16 (VHI OSC)	Open	R5 (VHI OSC)	0 Ω
C17 (VTU)	1 μF/50 V	R6 (VTU)	22 kΩ
C18 (IF OUT1)	2.2 nF	R7 (IFOUT2)	50 Ω
C19 (IF OUT2)	2.2 nF	R14 (VLO IN)	Open or 50 Ω
C20 (BAND SEL)	0.1 μF	R19 (MIXOUT)	Open
C21 (OSC OUT2)	2.2 nF	R51 (VHI OSC)	0 Ω
C22 (OSC OUT1)	2.2 nF	U1	SN761685
C23 (VCC)	0.1 μF	VC1 (UHF OSC)	1T363A
C24 (VHI IN2)	2.2 nF	VC2 (VLO OSC)	1T363A
C25 (VHI IN1)	2.2 nF	VC3 (VHI OSC)	1T363A
C27 (VLO IN)	2.2 nF		



Test Circuits



 $GC = 20log(Vout diff / V_{IN}) = 20log(V_{OUT} / V_{IN}) + 6$

Figure 12. VHF-L Conversion Gain-Measurement Circuit

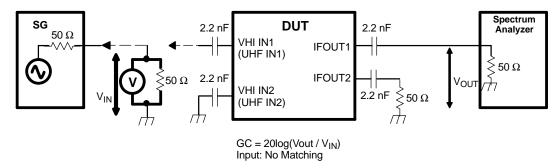


Figure 13. VHF-H, UHF-Conversion Gain-Measurement Circuit

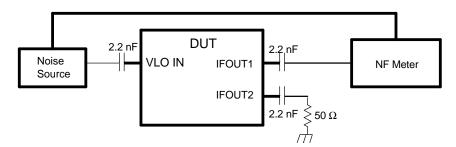


Figure 14. VHF-L Noise-Figure Measurement Circuit

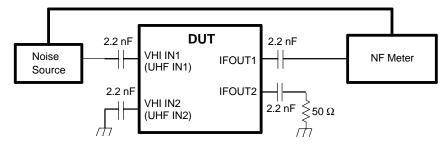


Figure 15. VHF-H, UHF Noise-Figure Measurement Circuit



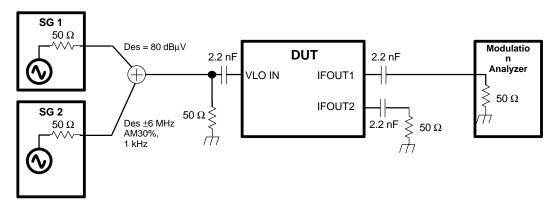


Figure 16. VHF-L 1% Cross-Modulation Distortion Measurement Circuit

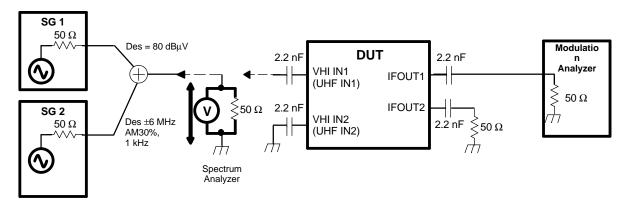


Figure 17. VHF-L 1% Cross-Modulation Distortion Measurement Circuit

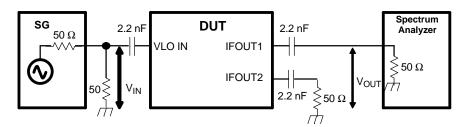


Figure 18. VHF-L Output Voltage Measurement Circuit

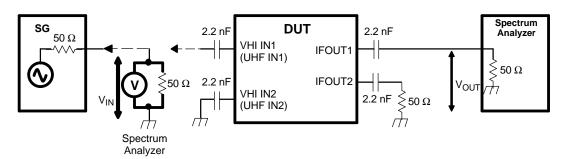


Figure 19. VHF-H, UHF Output Voltage Measurement Circuit



TYPICAL CHARACTERISTICS

S-Parameter

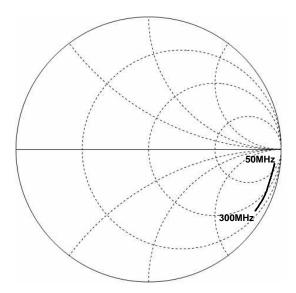


Figure 20. VLO IN

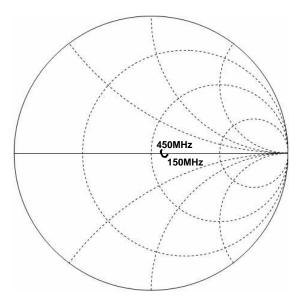


Figure 21. VH IN1,2



TYPICAL CHARACTERISTICS (continued)

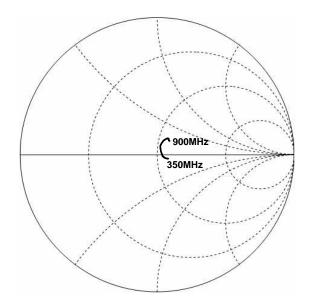


Figure 22. UHF IN1,2

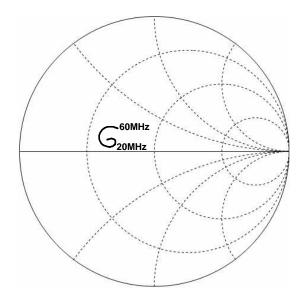
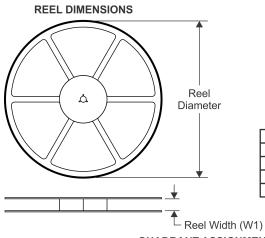


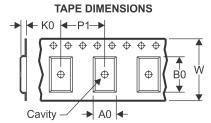
Figure 23. IFOUT1,2

PACKAGE MATERIALS INFORMATION

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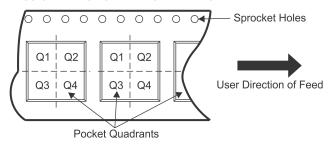
TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	Ν	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

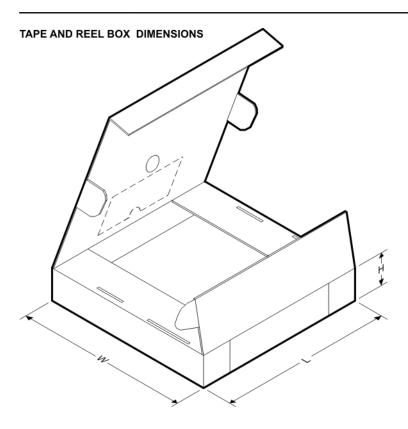


*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN761685PWR	TSSOP	PW	24	0	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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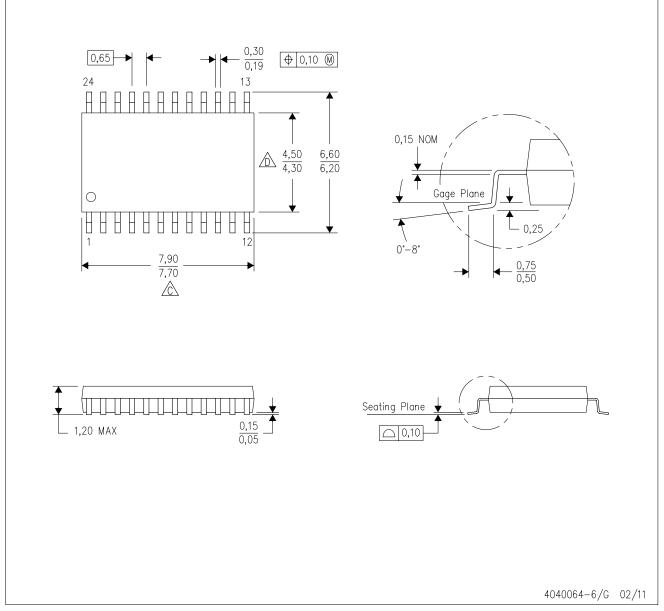


*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN761685PWR	TSSOP	PW	24	0	367.0	367.0	38.0	

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



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